

## Oxford Instruments, Plasmalab 80 plus



### *Capability/Application*

The Plasmalab 80 Plus is a plasma processing system which is configured to carry out reactive ion etching. The process recipes include etching SiO<sub>x</sub>, Si<sub>3</sub>N<sub>4</sub> and Polysilicon. The system is ideal for pilot line production, fast prototyping, development for optoelectronic and microelectronic applications.

### *Specifications*

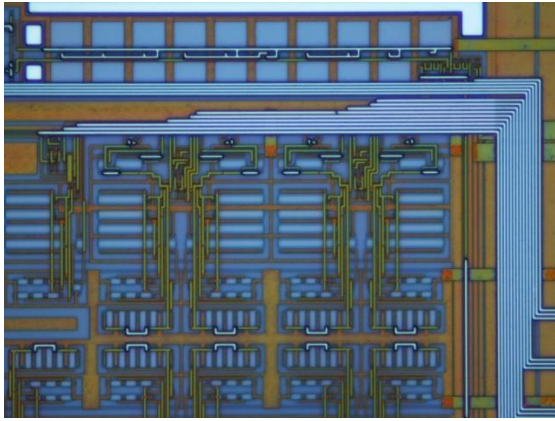
RF power range: 50-500W

Max gas flow rate: 100 sccm

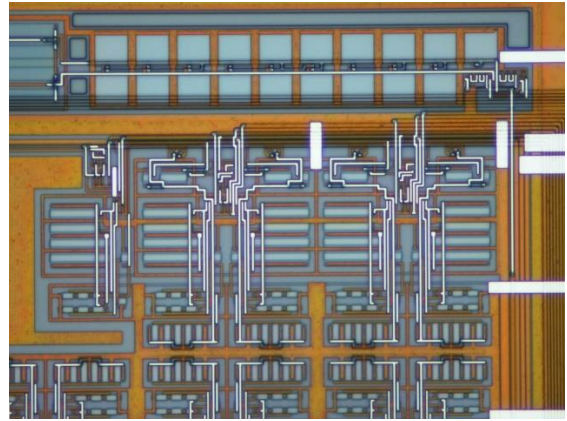
Max sample size: 200mm wafer

Installed gases: Oxygen, Argon, Carbon Tetrafluoride

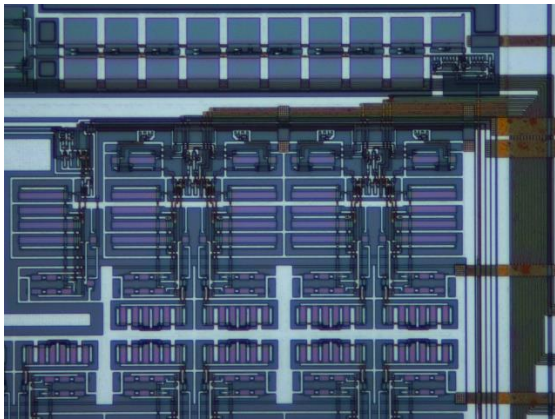
*Example application images*



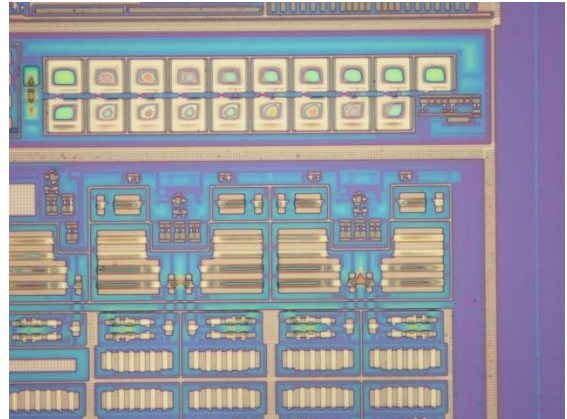
M3 metal layer



After M3 layer removal



After M2 layer removal



After M1 layer removal

*Youtube demo videos*

[https://www.youtube.com/watch?v=u5oh\\_as9v28](https://www.youtube.com/watch?v=u5oh_as9v28)